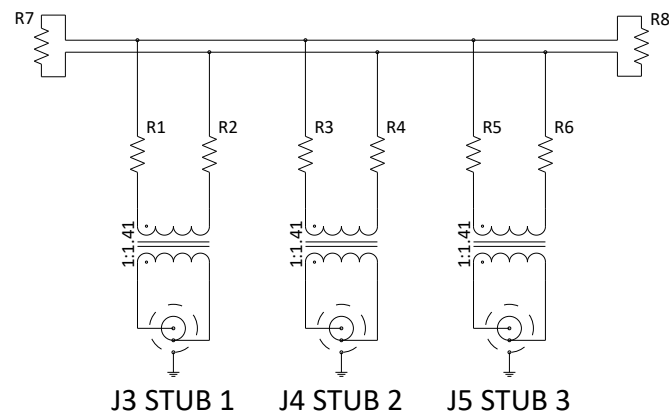


SCHEMATIC DIAGRAM



INTERMATEABILITY

CONNECTOR	RECOMMENDED MATING CONNECTOR
BJ770	PL75

1.0 ELECTRICAL SPECIFICATIONS: IAW MIL-STD-1553B

- 1.1 COMMON MODE REJECTION: -45.0 Db MAX @ 1.0MHz
- 1.2 DROOP: 20% MAX (250kHz)
- 1.3 OVERSHOOT & RINGING: ± 1.0V PEAK (250kHz SQUARE WAVE WITH 100Ns)
- 1.4 STUB VOLTAGE: 1.0V TO 14.0V P-P; LINE TO LINE; SIGNAL VOLTAGE, TRANSFORMER COUPLING
- 1.5 INPUT IMPEDANCE OF BUS: 3000 OHMS MIN. (75kHz - 1.0MHz), STUB WITH OPEN CIRCUIT
- 1.6 CHARACTERISTIC IMPEDANCE: Zo=78 OHMS
- 1.7 FAULT PROTECTION: 59 OHMS ± 1% 1W (R1-R6) IN SERIES WITH TRANSFORMER WINDING ON BUS SIDE
- 1.8 TERMINATION RESISTOR VALUE: 78.7 OHMS ± 1% 2W (R7, R8) BUS TERMINATION

2.0 MECHANICAL SPECIFICATIONS:

- 2.1 ENCLOSURE MATERIAL: AL 5754, 2MM THK.
FINISH: CHEMICAL FILM PER SI-0000-0036, CLASS 2
- 2.2 MOUNTING PLATE MATERIAL: AL 5754, 2MM THK.
FINISH: CHEMICAL FILM PER SI-0000-0036, CLASS 2

3.0 ENVIRONMENTAL SPECIFICATIONS:

- 3.1 OPERATING TEMPERATURE RANGE: -55°C TO 125°C
- 3.2 VIBRATION: MIL-STD-810G_CHG-1 METHOD 514.7 PROCEDURE I
- 3.3 SHOCK: MIL-STD-810G_CHG-1 METHOD 516.7 PROCEDURE V
- 3.4 HIGH TEMPERATURE OPERATING: MIL-STD-810G_CHG-1 METHOD 501.6 PROCEDURE II, +125°C
- 3.5 LOW TEMPERATURE OPERATING: MIL-STD-810G_CHG-1 METHOD 502.6 PROCEDURE II, -55°C
- 3.6 HIGH TEMPERATURE STORAGE: MIL-STD-810G_CHG-1 METHOD 501.6 PROCEDURE I, +125°C
- 3.7 LOW TEMPERATURE STORAGE: MIL-STD-810G_CHG-1 METHOD 502.6 PROCEDURE I, -55°C
- 3.8 RAIN: MIL-STD-810G METHOD 506.5 PROCEDURE I

UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS.				
PRODUCT NAME BOX TYPE BUS COUPLER 3 STUB DTRM				 www.delco.com.tr
DOCUMENT NAME DE8233 - TECHNICAL DRAWING				
SIZE A3	SCALE 1:1	REVISION 1	REVISION DATE 28.11.2023	SHEET 1/1